#### Mechanics for the 5<sup>th</sup> and 6<sup>th</sup> pixel layer

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#### **1.- Conceptual design**

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#### **Introduction**

- Much work on-going to (re)-define the ITK layout for Phase-2
	- ‣ *ITK Layout Task Force Workshop* (June, 23): https://indico.cern.ch/event/394897/ ๏ see Andi's summary talk in this workshop
- High-level functional requirements (ATL-COM-UPGRADE-2015-015) 1.- basic operational parameters
	- 2.- required tracking performance
		- $\circ$  pile-up robustness, coverage, track reco. efficiency (e,  $\mu$ ,  $\pi$ ), track parameter resolutions, occupancies, fake-rates, etc.
	- 3.- interface to the LHC machine (protection against beam losses)
	- 4.- interface to the rest of ATLAS
		- ๏ ITK conforming to TDAQ requirements, latencies, L1-track trigger, etc.
	- 5.- access scenarios
		- ๏ beam-pipe removal, inner pixel layers removal, whole pixel removal, whole ITK removal
	- 6.- mechanical constraints
	- 7.- electrical requirements,
		- ๏ power dissipation, noise occupancy, ESD protections, SEU, grounding & shielding, specs for components (cables, capacitors), etc.
- 8.- safety requirements (interlocks, etc.)<br>Sergio Gonzalez Sevilla (UniGe) 3 Sergio Gonzalez Sevilla (UniGe)

#### **Mechanical constraints**

- 6.1.- "*While meeting all different requirements, the goal is also to minimize the amount of material inside the ITK volume by careful choices of material and routing. The layout if ITK structures should take into account the feasibility of cable routing and the effect of that routing on the material budget and detector performance*".
	- ‣ material budget directly affecting the tracker performance
		- $\circ$  tracking resolution (low  $p_T$  tracks)
			- ❖ multiple scattering
		- ๏ tracking efficiency
			- ❖ pions: nuclear hadronic interactions
			- ❖ electrons: bremsstrahlung
	- ‣ passive material (services, mechanical support structure, interfaces) dominate over active material in the forward region  $|\eta|>1.5$ 
		- ๏ though typically everywhere in the detector: more sensors = more services

# **Positioning requirements**

ATU-SYS-ES-0027

- Hermeticity and overlaps
	- $\blacktriangleright$  ITK must be fully hermetic for 1 GeV p<sub>T</sub> tracks originating from a cylinder of length  $z = \pm 150$  mm along the beam direction.
	- ‣ Minimum overlap of 5 sensing elements (pixels or strips)
- Assembly tolerances
	- <u>local assembly placement accuracy</u> (between adjacent modules) of  $\pm 100 \mu m$
	- local assembly survey: comparable or better than the intrinsic sensor resolution
- Stability
	- ‣ directly to the track-based alignment strategy



### **SLIM concept (1/3)**

- Main motivation: strongly reduce the total amount of material along the track path in pixel layers at large radii
	- ‣ fulfilling tracking performance requirements and complying with mechanical constraints and positioning requirements
	- ‣ (classical) barrel-modules layout (// z-axis) + **inclined modules** for |η| > ~1.0 (Pixel layers 5 & 6)  $0.5$  1.0 1.5



- less services / dead material
- ‣ cost savings
- forwa forward<br>Sergio Gonzalez Sevilla (UniGe) 6 ► similar tracking performances, barrel / endcap transition region can be moved

#### **SLIM concept (2/3)**



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#### **SLIM concept (3/3)**

**Layers Radius (mm) Cooling Lines**  $\overline{\phantom{a}}$ **modules surface** les **stave (mm<sup>2</sup> ) (m2 ) Ratio surface (m2)** • Modules implemented on both sides of the carbon structure (Longeron)

**Total SLIM** 

**Number of**

- **3rd <sup>160</sup>** <sup>27</sup> <sup>24</sup> <sup>15</sup> **1.2** <sup>26</sup> <sup>80000</sup> **2.1** 0.56 **0.9 0** 2001) Superstermance Superstead Burns (Darrent in Superson Supersion Supersion Supersion Supersion Supersion Su  $\frac{1}{2}$  depending on layer pairs **8.6**  $\alpha$  **3.6**  $\alpha$  **4.6**  $\alpha$  **4** • same modures (barrer, tilled) for all<br>structures depending on layer pairs • Same modules (barrel, tilted) for all layers, but different types of support
- ▶ Layers 56: 3 types of longeron

**Number of** 

**Number of** 



- IBL experience on integration stand experimental experimental experimental experimental experimental experimental experimental experimental experim<br>The contract of the contract o
- Stave extracted radially with a combined kinematic  $\epsilon$  on megration stand













## **Cooling line**

- Simulation of cooling performance using CAD cells <sup>Ba</sup>
	- $\triangleright$  pipe with ∅2 ∅2.5 mm inner diameter OK (CO<sub>2</sub> cooling)  $\bigwedge_{\text{so} \downarrow}$  $\frac{1}{100}$  Maximum heat flux of 0.5 W.cm 2.5 W.cm  $\overline{2}$
	- stability of cooling temperature along longeron ±1°C



 $1000$ 

G  $MF$ 

60

80

100

Bart VERLAAT

 $\overline{\phantom{m}}$ 

▫ Modules distribution from CAD

• Based on:

 $\frac{1}{\sqrt{2}}$  maximum heat  $\frac{1}{\sqrt{2}}$  we have flux of  $\frac{1}{\sqrt{2}}$  we have  $\frac{1}{\sqrt{2}}$  we hav

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#### **Services routing**

• Module flex with pigtail



# **Material budget (1/2)**





#### **Material budget (2/2)** • Comparison of material budget: SLIM vs IBL ▶ R=164 mm, 2 m long stave ‣ rescale IBL position up to 164 mm ▶ only local supports, no silicon IBL nominal radius (~33 mm) IBL "rescaled"  $@R=164$  mm





#### **2.- Prototyping**

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# **Prototyping campaign for SLIM concept**

#### 1.- **Longeron**

- ‣ manufacturing
	- ๏ short section: transition region

#### **2.- Cooling lines**

- ‣ cooling pipe bending jig
- ‣ cooling line-to-longeron bonding jig

#### **3.- Module cells**

- ▶ cooling blocks production
- ‣ barrel cell assembly and loading
- ‣ tilted cell assembly and loading
	- ➡ measure thermo-mechanical performances of cell assembly

# **Cooling lines**

- ; pipe bending jig Cooling pipe bendin • Cooling pipe bending jig
	- Cooling line-to-longeron bonding jig
		- $\mathcal{L}$  cype (epoxy interface): americss:  $\bullet$  solbesive type  $\theta$  $\blacktriangleright$  adhesive type (epoxy film / glue) ? thickness ?



#### **Base- and cooling-block prototypes (1/2)**

- Aluminium-Carbon composite (60% Cf) from NovaPack (France)  $L$  figure  $C$  arbon composites  $(6.00/Cf)$  from
	- Al alloy poured into a matrix of carbon fibres grown with given fibre orientation
	- In-plane fibres alignment, low CTE (Si CTE: 2.6 ppm/°C)







#### **Base- and cooling-block prototypes (2/2)**

- PROTOTYPE MATERIAL • First prototypes already received, **extremely good quality**
	- ▶ e.g: specifications for base-block positioning pin diameter:  $[0.994 - 0.980]$  mm; metrology survey = 0.984 mm



 $\mathbf{R}$ 

**BARREL CELL**



#### **3.- Alternatives**

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#### **Upgrade of the ALICE ITS (1/2) ALICE**

- ALICE Inner Tracking System (ITS)
	- ▶ 7 layers with MAPS
		- ๏ Inner Barrel: 22, 31, 39 C
		- ๏ Outer Barrel: 194, 247, 353, 405
	- ▶ 10.3 m<sup>2</sup>,  $\sim$ 12.5 x 10<sup>9</sup> pixels with binary readout  $F_{1,1}$ ,  $F_{2,1}$ ,  $F_{3,2}$ ,  $F_{4,1}$ ,  $F_{5,1}$
- Operated at room temperature  $(20 30 \degree C)$ ,



Beam pipe

nner Barre

**Outer Barrel** 

# **Upgrade of the ALICE ITS (2/2)**

- Stave mechanical components:
- stave based on composite material (CFRP) ‣ **space-frame:** truss-like lightweight mechanical support structure for the single
	- **► cold-plate:** sheet of high-thermal conductivity CF laminate, with embedded polymide cooling pipes, ∅1.0(2.7) mm ID for IB(OB) staves



### SLIM + Truss structure (1/2)

- 1. Cooling lines + cooling pads attached to truss structure  $\cdot$  cooling lines  $\cdot$  cooling pads attached to truss  $\overline{C}$  and  $\overline{C}$  skin or sandwich to increase area and facilitate bonding) are and facilitate bonding  $\overline{C}$ ▫ Mechanical fixation system  $\mathbf{r}$  is controlled to trust structure to trust structure:
	- adhesive bonding skin or sandwich to increase and facilitate bonding  $\mathcal{L}_{\mathcal{B}}$
	-









### **SLIM + Truss structure (2/2)**

- 2. Flexible thermal strap for heat management  $\overline{\phantom{a}}$  and skin or sandwich to increase area and facilitate bonding  $\overline{\phantom{a}}$  $\sum_{n=1}^{\infty} \frac{1}{n} \sum_{n=1}^{\infty} \frac{1}{n}$ 2. Flexible thermal strap for heat managemen
	- I TPG plate behind module to minimise T within sensor within sensor  $\mathcal{L}$ 
		- ▶ Layered PGS (Pyrolytic Graphite Sheet) connecting TPG and cooling pads (floating pipes) and the strap for heat management of  $\mathbf{F}$
		- ▶ modules positioned on truss-structure via CFRP local supports  $\mathbf{D}_\mathbf{G}$  plate behind module to minimise  $\mathbf{D}_\mathbf{G}$  with sensor  $\mathbf{D}_\mathbf{G}$  within sensor  $\mathbf{D}_\mathbf{G}$  $\mathcal{L}^{\text{max}}$  connecting  $\mathcal{L}^{\text{max}}$  and cooling pads (floating pads (floating pads (floating pipes))





#### **Summary**

- Still a number of uncertainties in the layout of the future ITK
	- ‣ hopefully to be solved soon
- SLIM has been presented as a possible engineering solution for the outermost pixel layers of the ITK tracker
	- ‣ large benefits from using inclined sensors
		- ๏ large reduction in material budget
		- ๏ large reduction in cost
- First real prototypes currently being developed
	- ‣ evaluation of thermal and thermo-mechanical performances
	- ▶ comparison with detailed FEA simulations
	- validation of different component types and assembly techniques (pipe bonding)
- Further optimization of the layout after feedback from physics simulations

# **Thanks for your attention !**



#### **Electrical requirements**

- 7.2.- "**Power dissipation** per detector module must be low enough to prevent thermal runaway of Pixel and Strip sensors defined in conjunction woth the cooling capacity specification. Power dissipation of end of stave or petal circuitry must be low enough to prevent a rise in stave or petal temperature above that required for the attached modules to present their sensor thermal runaway".
- 7.3.- "**Noise occupancy** of the Pixel and Strip detectors should be at least one and preferably two orders of magnitude less than the occupancy due to hits on tracks after exposure to lifetime irradiation".

#### **SLIM with CFRP Truss structure: baseline**



#### **SLIM with CFRP Truss structure: alternative**

CFRP Truss Structure: Alternative Solution





### **CMS layout options**

#### CMS Tracker layout options





# **CMS layout options**

#### CMS Tracker layout options





- **‣ Pixel modules**
- ‣ **PS modules** (OT)
- ‣ **2S modules** (OT)



#### **• Tilted geometry**

- **‣ Pixel modules**
- ‣ **PS modules** (OT)
- ‣ **2S modules** (OT)

### **CMS layout options**

Gain of tilted wrt flat (simpler) geometry





37 12

#### **Engineering solutions for tilted modules: CMS** is for filted moMules: (





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